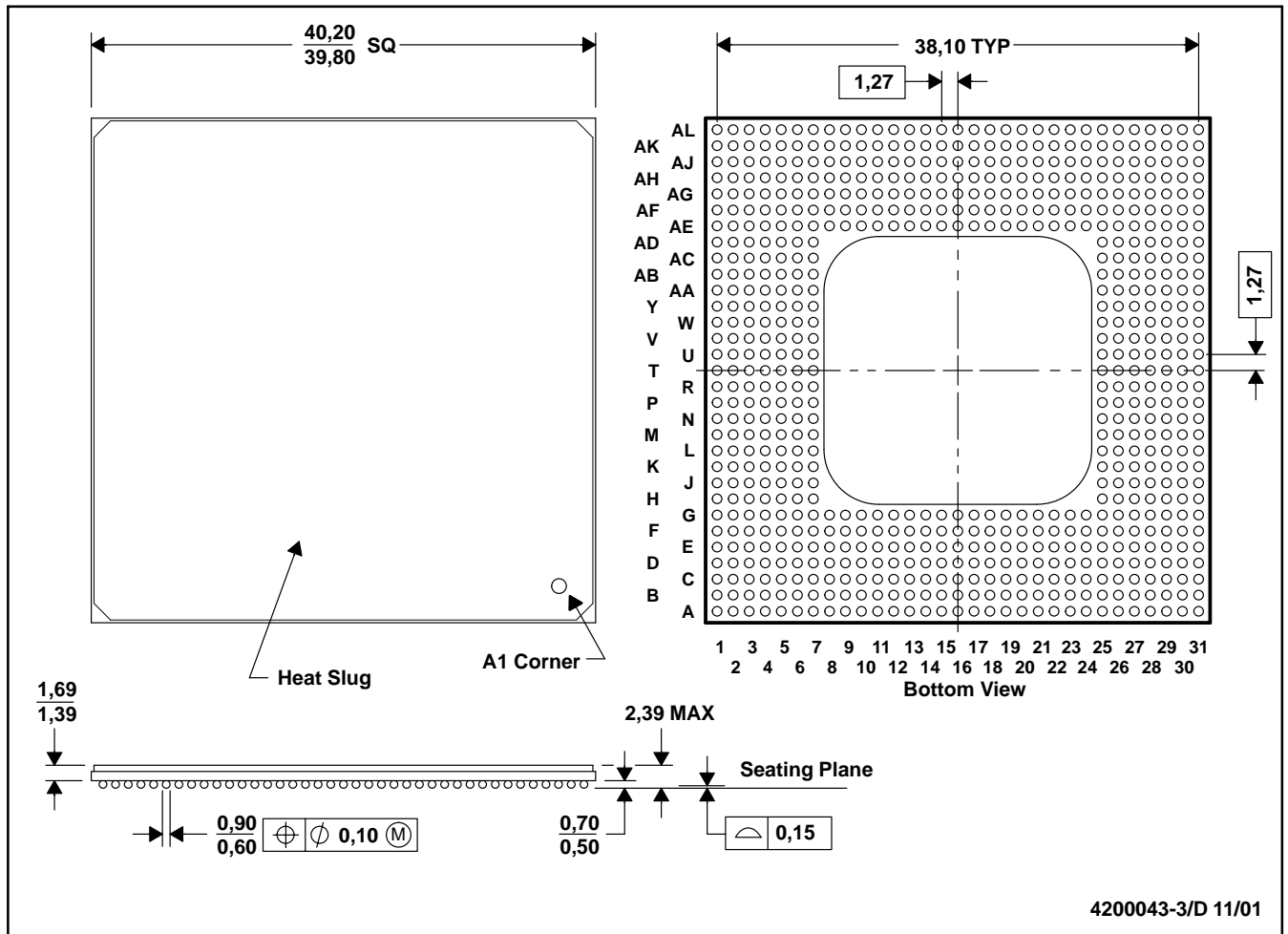


GKP (S-PBGA-N672)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced plastic package with metal heat slug (HSL)

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